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TECHNOLOGY CENTER 2800

In the claims:

Amend the following claims:

1. A laser diode arrangement, comprising a joint electrically insulating substrate, a plurality of laser diodes arranged in said joint electrically [insulated] insulating substrate; conductor structure provided on said electrically insulating substrate and connecting said laser diodes [are connected] with one another in series [through said conductor structures]; and means for joint control of said laser diodes.
2. A laser diode arrangement as defined in claim; and further comprising a support on which said substrate is located, wherein said substrate is composed of a material with high thermal conduction coefficient and a good thermal coupling to said support.
3. A laser diode arrangement as defined in claim; and further comprising a support on which said substrate is located, wherein said support is formed as a cooling body.
4. A laser diode arrangement as defined in claim; and further

comprising a support on which said substrate is located, wherein said support is in a thermal contact with the cooling body.

6. A laser diode arrangement as defined in claim 1, wherein said laser diodes have first electrodes which directly contact said conductor structures [and], said laser diodes also have second electrodes which contact said conductor structures through first bond wires.

7. A laser diode arrangement as defined in claim [1] 6; and further comprising a support on which said substrate is located; and further conductor structures applied on said support and contacting with said first-mentioned conductor structures on said substrate through second bond wires.

Amended claims:

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sub B1 > 1. A laser diode arrangement, comprising a joint electrically insulating substrate, a plurality of laser diodes arranged in said joint electrically insulating substrate; conductor structure provided on said electrically insulating substrate and connecting said laser diodes with one another in series; and means for joint control of said laser diodes.

2. A laser diode arrangement as defined in claim 1; and further comprising a support on which said substrate is located, wherein said substrate is composed of a material with high thermal conduction coefficient and a good thermal coupling to said support.

3. A laser diode arrangement as defined in claim 1; and further comprising a support on which said substrate is located, wherein said support is formed as a cooling body.

4. A laser diode arrangement as defined in claim 1; and further comprising a support on which said substrate is located, wherein said support is in a thermal contact with the cooling body.

6. A laser diode arrangement as defined in claim 1, wherein said laser diodes have first electrodes which directly contact said conductor structures, said laser diodes also have second electrodes which contact said conductor structures through first bond wires.

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sub B2 > 7. A laser diode arrangement as defined in claim 6; and further comprising a support on which said substrate is located; and further conductor structures applied on said support and contacting with said first mentioned conductor structures on said substrate through second bond wires.